

CLAIMS

1. A laminated ceramic electronic component comprising an inner conductor provided inside of a ceramic laminated product, an outer electrode provided on the surface of the ceramic laminated product, and a leading conductor connecting the inner conductor to the outer electrode,

wherein the thickness of the leading conductor is smaller than the thickness of the inner conductor.

2. The laminated ceramic electronic component according to claim 1, wherein the conductor width of the leading conductor is larger than the conductor width of the inner conductor.

3. The laminated ceramic electronic component according to claim 1 or claim 2, wherein the inner conductor is a conductor for a coil.

4. A method for producing a laminated ceramic electronic component including a ceramic laminated product formed by laminating a plurality of ceramic green sheets, an inner conductor formed inside of the ceramic laminated product, an outer electrode formed on the surface of the ceramic laminated product, and a leading conductor connecting the inner conductor to the outer electrode, the method comprising the steps of:

preparing the ceramic green sheets;

transferring an inner conductor pattern layer and a

leading conductor pattern layer formed on a support on the ceramic green sheets in order to form the inner conductor and the leading conductor on the ceramic green sheets;

laminating the ceramic green sheets so as to cover the inner conductor and the leading conductor; and

firing the ceramic laminated product,

wherein, in the step of forming the inner conductor and the leading conductor, the inner conductor pattern layer is transferred on the ceramic green sheet a plurality of times so as to overlap each other, thereby forming the inner conductor, and the leading conductor pattern layer is transferred on the ceramic green sheet, wherein the number of times of the transferring is smaller than the number of times of the transferring of the inner conductor pattern layer, thereby forming the leading conductor having a thickness smaller than the thickness of the inner conductor.

5. The method for producing a laminated ceramic electronic component according to claim 4, wherein the ceramic laminated product formed by laminating a plurality of ceramic green sheets is a mother ceramic laminated block composed of a plurality of ceramic laminated products, and the mother ceramic laminated block is cut according to the arrangement of the inner conductor formed inside thereof to provide each ceramic laminated product.

6. The method for producing a laminated ceramic

electronic component according to claim 4 or claim 5, wherein the conductor width of the leading conductor is larger than the conductor width of the inner conductor.

7. The method for producing a laminated ceramic electronic component according to any one of claims 4 to 6, wherein the metal content of conductive paste used for forming the leading conductor pattern layer is higher than that of conductive paste used for forming the inner conductor pattern layer.

8. The method for producing a laminated ceramic electronic component according to any one of claims 4 to 7, wherein, among the inner conductor pattern layers, at least the inner conductor pattern layer that is brought into contact with the ceramic green sheet is formed with conductive paste including resin particles that are lost by being fired in the firing step.